SN54HC174, SN74HC174 HEX D-TYPE FLIP-FLOPS WITH CLEAR SCLS119B – DECEMBER 1982 – REVISED MAY 1997

- Contain Six Flip-Flops With Single-Rail Outputs
- Applications Include:
 - Buffer/Storage Registers
 - Shift Registers
 - Pattern Generators
- Package Options Include Plastic Small-Outline (D) and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

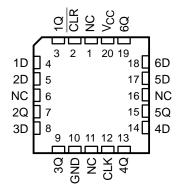
These monolithic positive-edge-triggered D-type flip-flops have a direct clear (CLR) input.

Information at the data (D) inputs meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going edge of CLK. When CLK is at either the high or low level, the D input has no effect at the output.

The SN54HC174 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74HC174 is characterized for operation from -40° C to 85° C.

SN54HC174 J OR W PACKAGE SN74HC174 D OR N PACKAGE (TOP VIEW)									
CLR [1	16	V _{CC}						
1Q [2	15	6Q						
1D [3	14	6D						
2D [4	13	5D						
2Q [5	12	5Q						
3D [6	11	4D						
3Q [7	10	4Q						
GND [8	9	CLK						

SN54HC174 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

	(each flip-flop)										
	INPUTS	OUTPUT									
CLR	CLK	D	Q								
L	Х	Х	L								
н	\uparrow	Н	н								
н	\uparrow	L	L								
н	L	Х	Q ₀								

FUNCTION TABLE



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

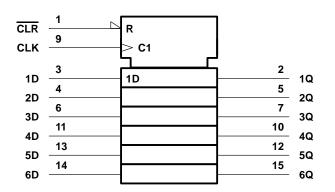
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



SN54HC174, SN74HC174 **HEX D-TYPÉ FLIP-FLOPS** WITH CLEAR

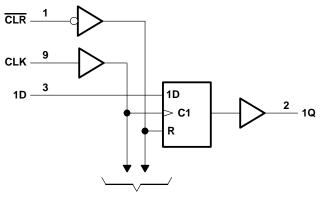
SCLS119B - DECEMBER 1982 - REVISED MAY 1997

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, N, and W packages.

logic diagram (positive logic)



To Five Other Channels

Pin numbers shown are for the D, J, N, and W packages.

absolute maximum ratings over operating free-air temperature range[‡]

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	113°C/W
N package	
Storage temperature range, T _{stg}	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.



recommended operating conditions

			SI	SN54HC174			SN74HC174		
						MAX			
VCC	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
VIH	VIH High-level input voltage	$V_{CC} = 4.5 V$	3.15			3.15			V
		ACC = 6 A	4.2			4.2			
		$V_{CC} = 2 V$	0		0.5	0		0.5	
VIL	Low-level input voltage	$V_{CC} = 4.5 V$	0		1.35	0		1.35	V
		ACC = 6 A	0		1.8	0		1.8	
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
		$V_{CC} = 2 V$	0		1000	0		1000	
t _t Input transition (rise and	Input transition (rise and fall) time	$V_{CC} = 4.5 V$	0		500	0		500	ns
		$V_{CC} = 6 V$	0		400	0		400	
TA	Operating free-air temperature		-55		125	-40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vaa	Т	A = 25°C	;	SN54HC174		SN74HC174		UNIT
PARAMETER	TEST CC	INDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
VOH	$V_I = V_{IH} \text{ or } V_{IL}$		6 V	5.9	5.999		5.9		5.9		V
		I _{OH} = -4 mA	4.5 V	3.98	4.3		3.7		3.84		
		I _{OH} = -5.2 mA	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
			I _{OL} = 20 μA 4.5 V 0.001	0.001	0.1		0.1		0.1		
VOL	$V_I = V_{IH} \text{ or } V_{IL}$		6 V		0.001	0.1		0.1		0.1	V
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
lı	$V_I = V_{CC} \text{ or } 0$		6 V		±0.1	±100		±1000		±1000	nA
ICC	$V_{I} = V_{CC} \text{ or } 0,$	I ^O = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF



timing requirements over recommended operating free-air temperature range (unless otherwise	е
noted)	

			Vee	T _A =	25°C	SN54H	IC174	SN74H	IC174	UNIT
			Vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	0	6	0	4.2	0	5	
^f clock	Clock frequency		4.5 V	0	31	0	21	0	25	MHz
			6 V	0	36	0	25	0	29	
t _w Pulse duration		2 V	80		120		100			
	CLR low	4.5 V	16		24		20			
		6 V	14		20		17			
	ruise duration	CLK high or low	2 V	80		120		100		ns
			4.5 V	16		24		20		
			6 V	14		20		17		
			2 V	100		150		125		ns
		Data	4.5 V	20		30		25		
	Setur time before CLK ¹		6 V	17		25		21		
t _{su}	Setup time before CLK↑		2 V	100		150		125		
		CLR inactive	4.5 V	20		30		25		
			6 V	17		25		21		
			2 V	0		0		0		ns
t _h	Hold time, data after $CLK{\uparrow}$		4.5 V	0		0		0		
			6 V	0		0		0		

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	Vaa	Т	T _A = 25°C		SN54HC174		SN74HC174		UNIT
PARAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
			2 V	6	9		4.2		5		
f _{max}			4.5 V	31	44		21		25		MHz
			6 V	36	50		25		29		
			2 V		58	160		240		200	
	CLR	Any	4.5 V		17	32		48		40	
. .			6 V		14	27		41		34	
^t pd	CLK	Any	2 V		58	160		240		200	ns
			4.5 V		17	32		48		40	
		6 V		14	27		41		34		
		Any	2 V		38	75		110		90	
tt			4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance per flip-flop	No load	27	pF



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Vcc **High-Level** 50% 50% Pulse **From Output** Test 0 V Under Test Point C_L = 50 pF Vcc Low-Level (see Note A) 50% 50% Pulse 0 V LOAD CIRCUIT VOLTAGE WAVEFORMS PULSE DURATIONS Vcc 50% Input 50% 0 V ^tPLH ⁻ ^tPHL - Vcc VOH In-Phase Reference 90% 90% 50% 50% -_<u>10%</u> V_{OL} 50% Output Input 0 V – tf t_{su} ->>+ th ↓ tPHL ^tPLH - Vcc VOH Data 90% 90% 90% 90% 50% **Out-of-Phase** 50% 50% ⊾10% 50% Input <u>10%</u> o v Output VOL — tf - tr – tғ tr **VOLTAGE WAVEFORMS VOLTAGE WAVEFORMS** SETUP AND HOLD AND INPUT RISE AND FALL TIMES PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_r = 6 ns, t_f = 6 ns.
- C. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tPLH and tPHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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